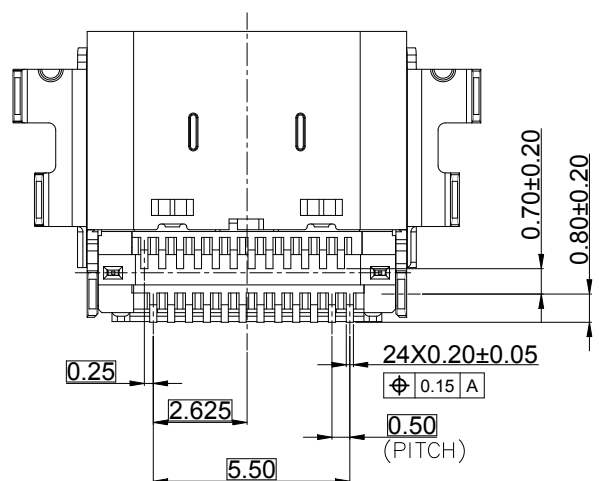
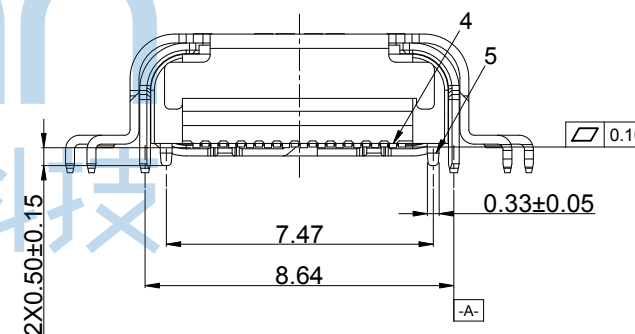
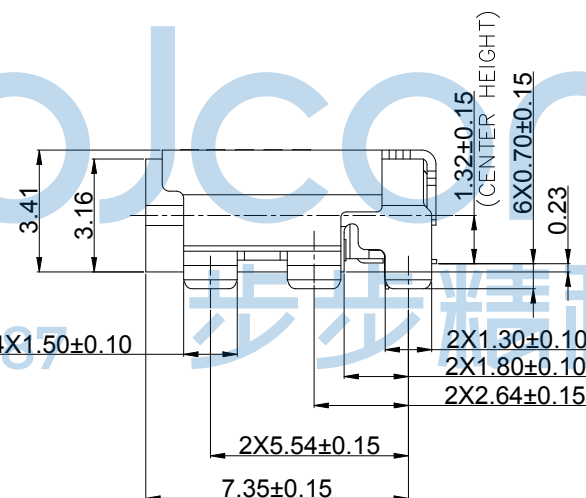
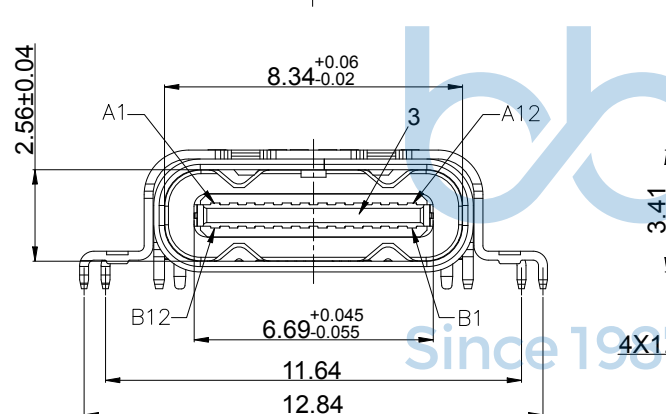
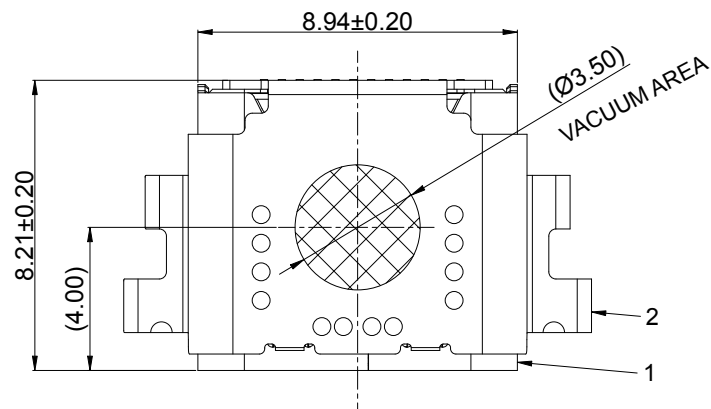


REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP

NOTE/注释:

1. SPECIFICATION/规格:

- 1.1 Rated current (额定电流): 5.0 A
- 1.2 Voltage rating (额定电压): 5V AC
- 1.3 Contact Resistance (接触阻抗): 40 m Ω Max.
- 1.4 Insulation Resistance (绝缘阻抗): 100MΩ Min.
- 1.5 Withstanding voltage (耐电压): 100 VAC/minute
- 1.6 Mating force (插入力): 5~20N.
- 1.7 Unmating force (拔出力): 8~20N.
- 1.8 Durability Cycle(寿命循环): 10,000 cycle
- 1.9 Operating temperature (工作温度): -40°~+85°

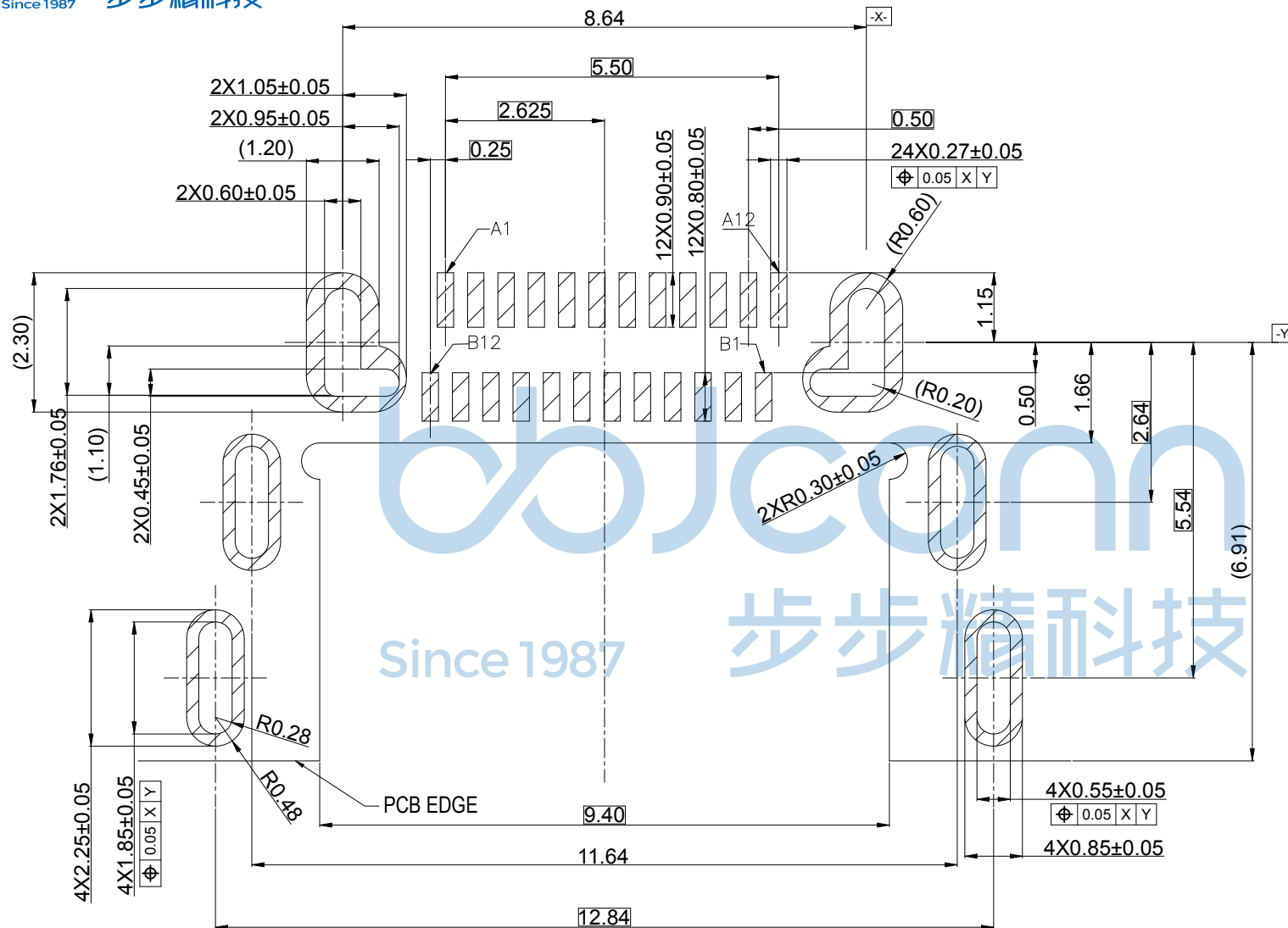


PIN ASSIGNMENT

A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12
GND	TX1+	TX1-	Vbus	CC1	D+	D-	SBU1	Vbus	RX2-	RX2+	GND
B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1
GND	RX1+	RX1-	Vbus	SBU2	D-	D+	CC2	Vbus	TX2-	TX2+	GND



THIS DOCUMENT IS THE SOLE PROPERTY OF BBJconn Technology Co.,Ltd. Corporation AND SHOULD NOT BE USED IN WHOLE OR IN PART WITHOUT PRIOR WRITTEN PERMISSION. PDWG.NO: 0470-1		深圳市步步精科技有限公司					
		.X: ±0.38 .XX: ±0.25 .XXX: ±0.13		X*: ±3* .X*: ±2* .XX*: ±1*			
	NAME: U4 40G速率 TYPE-C 24P 母座 有后盖 双壳 六脚插 双排SMT 沉板0.23 L=8.21				PJ. NO.: 126-223-240009-U4G		
	APPD. JM_Zheng	CHKD. LYX		FINISH: SEE NOTES		MAT'L.: SEE NOTES	
	DR. TSP	SCALE: N/A		REV.: A0		UNIT: mm	



5	MID PLATE	1	SUS301-H	30U" NICKEL PLATING	T=0.15
4	TERMINAL	24	COPPER ALLOY	MATING SIDE: Au1u"; SOLDER TAIL: Gold FLASH, 50u" NICKEL OVERALL.	T=0.12
3	MAIN HOUSING		HIGH TEMPERATURE	PAST BLACK	UL94V-0
2	OUT SHELL	1	STAINLESS STEEL	30U" NICKEL PLATING	T=0.25
1	MAIN SHELL	1	STAINLESS STEEL	30U" NICKEL PLATING	T=0.30
ITEM	DESCRIPTION	Q'TY	MATERIAL	FINISH	REMARK
BILL OF MATERIAL					

THIS DOCUMENT IS THE
SOLE PROPERTY OF
BBJconn Technology Co.,Ltd
Corporation AND SHOULD
NOT BE USED IN WHOLE
OR IN PART WITHOUT
PRIOR WRITTEN PERMISSION.

PDWG,NO: 0470-1



深圳市步步精科技有限公司

.X: ± 0.38	X*: $\pm 3^\circ$
.XX: ± 0.25	.X*: $\pm 2^\circ$
.XXX: ± 0.13	.XX*: $\pm 1^\circ$

NAME: U4 40G速率 TYPE-C 24P 母座 有后盖
双壳 六脚插 双排SMT 沉板0.23 L=8.21

APPD.	JM_Zheng
-------	----------



PJ. NO.: 126-223-240009-U4G

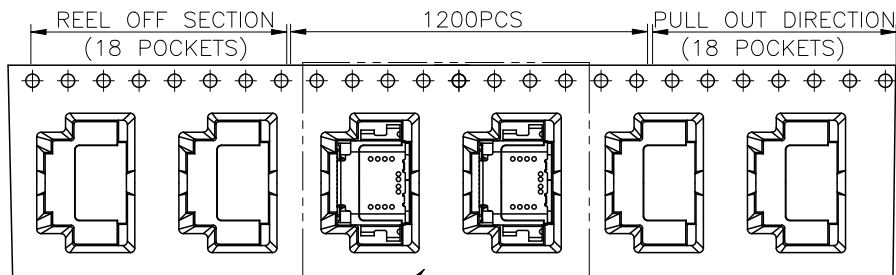
CHKD. LYX

SIZE: A4 | DRW NO.:

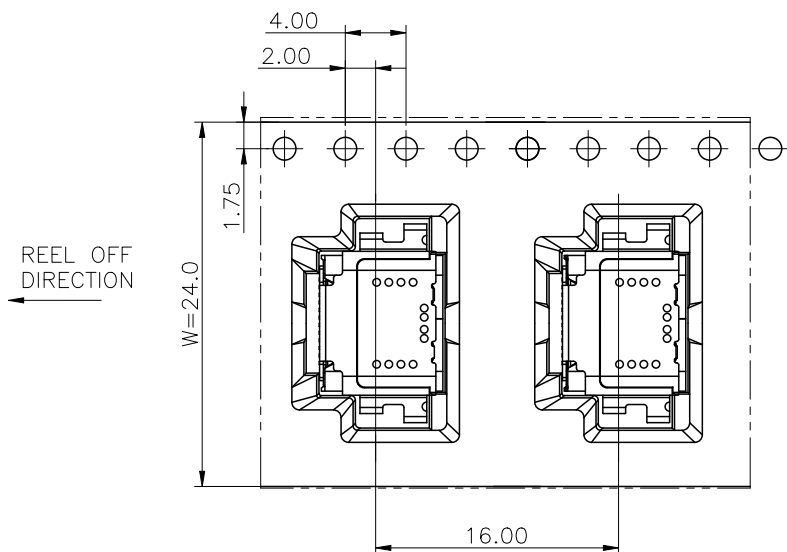
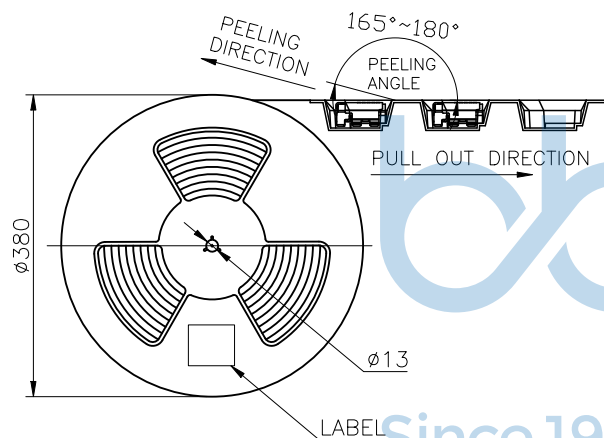
DR.	TSP
-----	-----

FINISH: SEE NOTES	MAT'L.: SEE NOTES
-------------------	-------------------

SCALE: N/A	REV.: A0	UNIT: mm	PAGE: 2/3
------------	----------	----------	-----------



SEE DETAIL X



PAPER BOARD

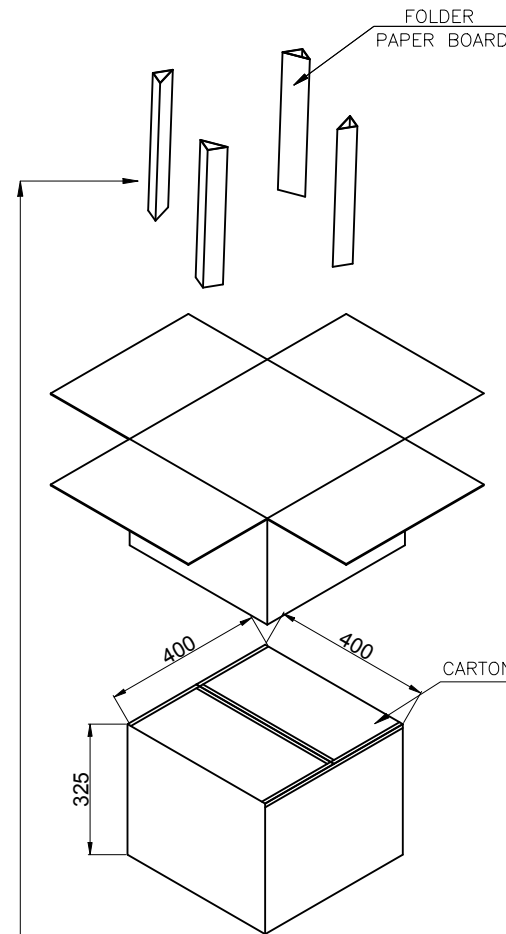
REEL AND TAPE

REEL AND TAPE

PAPER BOARD



REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



	REEL	CARTON
CONNECTOR (PCS)	1200	12000

THIS DOCUMENT IS THE
SOLE PROPERTY OF
BBJconn Technology Co.,Ltd.
Corporation AND SHOULD
NOT BE USED IN WHOLE
OR IN PART WITHOUT
PRIOR WRITTEN PERMISSION.
PDWG.NO: 0470-1



深圳市步步精科技有限公司

.X: ± 0.38
.XX: ± 0.25
.XXX: ± 0.13

X': $\pm 3'$
.X': $\pm 2'$
.XX': $\pm 1'$

NAME: U4 40G速率 TYPE-C 24P 母座 有后盖
双壳 六脚插 双排SMT 沉板0.23 L=8.21

APPD. JM_Zheng
CHKD. LYX
DR. TSP

PJ. NO.: 126-223-240009-U4G
SIZE: A4 DRW NO.:
FINISH: SEE NOTES MAT'L.: SEE NOTES
SCALE: N/A REV.: A0 UNIT: mm PAGE: 3/3